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MTP3055VL

N-Channel Logic Level Enhancement Mode Field Effect Transistor

General Description

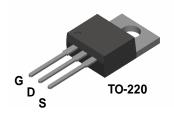
This N-Channel Logic Level MOSFET has been designed specifically for low voltage, high speed switching applications i.e. power supplies and power motor controls.

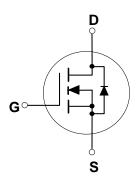
This MOSFET features faster switching and lower gate charge than other MOSFETs with comparable $R_{\text{DS(ON)}}$ specifications.

The result is a MOSFET that is easy and safer to drive (even at very high frequencies).

Features

- 12 A, 60 V. $R_{DS(ON)} = 0.18 \Omega @ V_{GS} = 5 V$
- Critical DC electrical parameters specified at elevated temperature.
- Low drive requirements allowing operation directly from logic drivers. Vgs(th) < 2 V.
- Rugged internal source-drain diode can eliminate the need for an external Zener diode transient suppressor.
- 175°C maximum junction temperature rating.





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter	Ratings	Units	
V _{DSS}	Drain-Source Voltage	60	V	
V _{GSS}	Gate-Source Voltage	<u>+</u> 15	V	
I _D	Drain Current - Continuous	12	A	
	- Pulsed	42		
P _D	Power Dissipation @ T _C = 25°C	48	W	
	Derate above 25°C	0.32	W/°C	
T _J , T _{STG}	Operating and Storage Junction Temperature Range	-65 to +175	∘C	
<u> Thermal</u>	Characteristics			
$R_{\theta JC}$	Thermal Resistance, Junction-to- Case	3.13	°C/W	
R _{AJA}	Thermal Resistance, Junction-to- Ambient (Note 1)	62.5	∘C/W	

Package Outlines and Ordering Information

Device Marking	Device	Package Information	Quantity
MTP3055VL	MTP3055VL	Rails/Tubes	45 units

^{*} Die and manufacturing source subject to change without prior notification.

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
DRAIN-S	OURCE AVALANCHE RATI	NGS (Note 2)		•	•	•
W _{DSS}	Single Pulse Drain-Source Avalanche Energy	V _{DD} = 25 V, I _D = 12 A			72	mJ
I _{AR}	Maximum Drain-Source Avalanche	e Current			12	А
Off Chara	cteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	60			V
$\Delta BV_{DSS} \over \Delta T_{J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$, Referenced to 25°C		55		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$			10	μΑ
		$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 150^{\circ}\text{C}$			100	
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 15 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -15 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Chara	cteristics (Note 2)					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1	1.6	2	V
$\Delta V_{GS(th)} = \Delta T_{.1}$	Gate Threshold Voltage Temperature Coefficient	I_D = 250 μ A, Referenced to 25°C		-4		mV/°C
R _{DS(on)}	Static Drain-Source On-Resistance	$V_{GS} = 5 V, I_D = 6 A,$		0.100	0.180	Ω
$V_{DS(on)}$	Drain-Source On-Voltage On-Resistance	$V_{GS} = 5 \text{ V}, I_{D} = 12 \text{ A}$			2.6	V
g _{FS}	Forward Transconductance	$V_{DS} = 8 \text{ V}, I_{D} = 6 \text{ A}$	5	8.7		S
Dvnamic	Characteristics					
C _{iss}	Input Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$		345	570	pF
Coss	Output Capacitance	f = 1.0 MHz		110	160	pF
C_{rss}	Reverse Transfer Capacitance			30	40	pF
Switching	Characteristics (Note 2)					
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 30 \text{ V}, I_{D} = 12 \text{ A},$			20	ns
t _r	Turn-On Rise Time	$V_{GS} = 5 \text{ V}, R_{GEN} = 9.1 \Omega$			190	ns
t _{d(off)}	Turn-Off Delay Time				30	ns
t _f	Turn-Off Fall Time	1			90	ns
Q _g	Total Gate Charge	V _{DS} = 48 V,		7.8	10	nC
Q _{gs}	Gate-Source Charge	I _D = 12 A, V _{GS} = 5 V		1.7		nC
Q _{gd}	Gate-Drain Charge			3.2		nC
					ı	
	urce Diode Characteristics Maximum Continuous Drain-Source				12	A
I _{SM}	Maximum Pulsed Drain-Source Di				42	A
V _{SD}	Drain-Source Diode Forward	$V_{GS} = 0 \text{ V}, I_S = 12 \text{ A}$ (Note 2)			1.3	V
→ 2D	Voltage	VGS - V V, IS - IZ / (NOIE 2)			1.5	_ <u> </u>
t _{rr}	Drain-Source Reverse Recovery Time	I _F =12 A, di/dt = 100A/μs		55		nS

^{1.} $R_{0,JA}$ is the sum of the juntion-to-case and case-to-ambient thermal resistance. 2. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%

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Stealth™

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Definition of Terms

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